

## ABSTRACT

The invention concerns multilayered structures useful for forming capacitors, which may be embedded within printed circuit boards or other microelectronic devices. The multilayered structure comprises a pair of parallel electrically conductive layers separated by a pair of dielectric layers and a central polymerizable layer. Each of the dielectric layers and the central layer may include a filler. Capacitors formed from the multilayered structures of the invention exhibit excellent short circuit resistance as well as excellent void resistance.